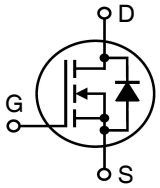
IXYS

Polar3™ HiPerFET™ Power MOSFET

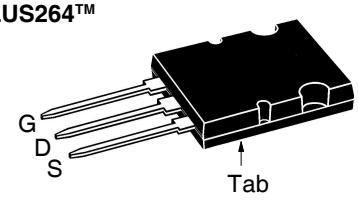
IXFB210N30P3

V_{DSS} = 300V
I_{D25} = 210A
$R_{DS(on)}$ ≤ 14.5mΩ
t_{rr} ≤ 250ns



N-Channel Enhancement Mode
Avalanche Rated
Fast Intrinsic Rectifier

PLUS264™



G = Gate D = Drain
S = Source Tab = Drain

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C	300	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ	300	V
V_{GSS}	Continuous	±20	V
V_{GSM}	Transient	±30	V
I_{D25}	T_C = 25°C (Chip Capability)	210	A
$I_{L(RMS)}$	External Lead Current Limit	160	A
I_{DM}	T_C = 25°C, Pulse Width Limited by T_{JM}	550	A
I_A	T_C = 25°C	105	A
E_{AS}	T_C = 25°C	4	J
dv/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$	35	V/ns
P_D	T_C = 25°C	1890	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
F_C	Mounting Force	30..120/6.7..27	N/lb
Weight		10	g

Features

- Dynamic dv/dt Rating
- Avalanche Rated
- Fast Intrinsic Rectifier
- Low $R_{DS(on)}$
- Low Drain-to-Tab Capacitance
- Low Package Inductance

Advantages

- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- Uninterrupted Power Supplies
- AC Motor Drives
- High Speed Power Switching Applications

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = 3mA	300			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8mA	2.5		5.0	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±200	nA
I_{DSS}	$V_{DS} = V_{DSS}$, V_{GS} = 0V			50	μA
	T_J = 125°C			1.5	mA
$R_{DS(on)}$	V_{GS} = 10V, $I_D = 0.5 \bullet I_{DSS}$, Note 1			14.5	mΩ

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = 10V, I_D = 60A, Note 1	60	100		S
C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		16.2		nF
C_{oss}			2550		pF
C_{rss}			42		pF
R_{Gi}	Gate Input Resistance		1.0		Ω
$t_{d(on)}$	**Resistive Switching Times**		46		ns
t_r	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{DSS}		25		ns
$t_{d(off)}$	R_G = 1Ω (External)		94		ns
t_f			13		ns
$Q_{g(on)}$	V_{GS} = 10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{DSS}		268		nC
Q_{gs}			80		nC
Q_{gd}			72		nC
R_{thJC}				0.066	°C/W
R_{thCS}			0.13		°C/W

Source-Drain Diode

Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			210	A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			840	A
V_{SD}	I_F = 100A, V_{GS} = 0V, Note 1			1.5	V
t_{rr}	I_F = 105A, -di/dt = 100A/μs			250	ns
Q_{RM}	V_R = 100V, V_{GS} = 0V		4.1		μC
I_{RM}			28		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

Fig. 1. Output Characteristics @ T_J = 25ºC

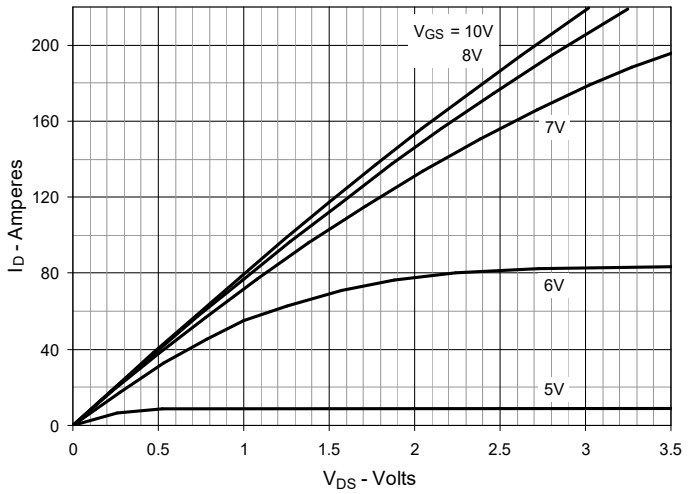


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

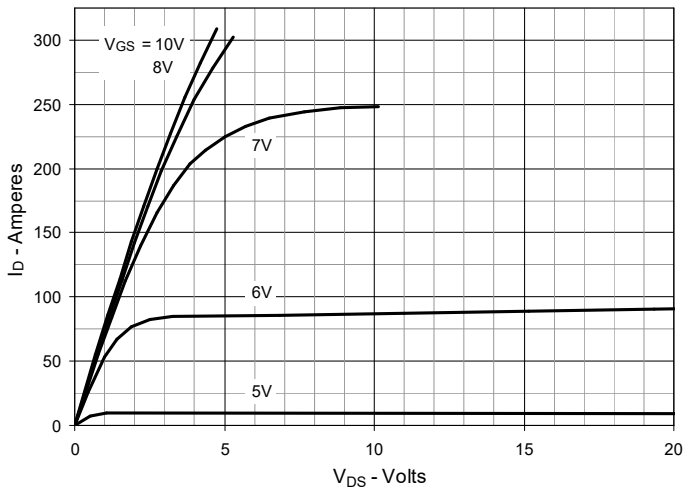


Fig. 3. Output Characteristics @ T_J = 125ºC

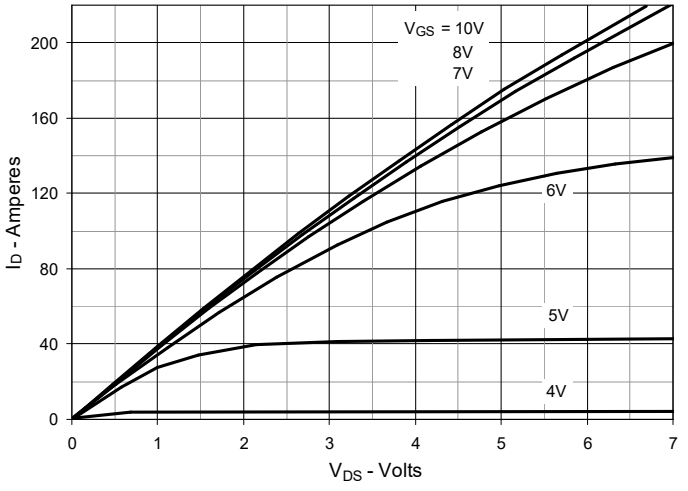


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 105A Value vs. Junction Temperature

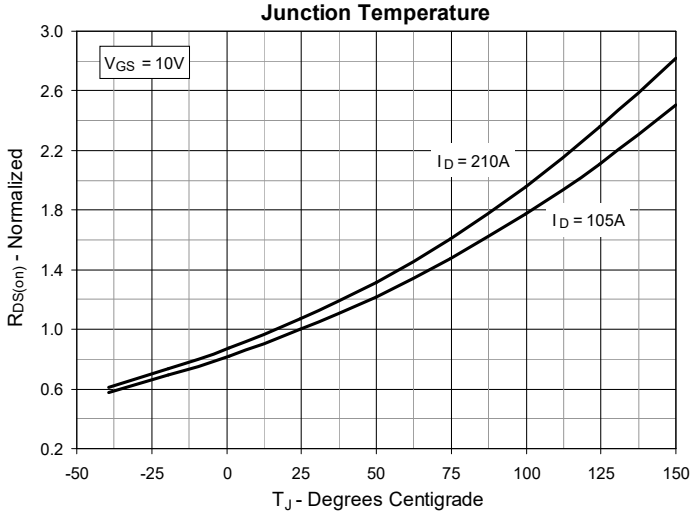


Fig. 5. $R_{DS(on)}$ Normalized to I_D = 105A Value vs. Drain Current

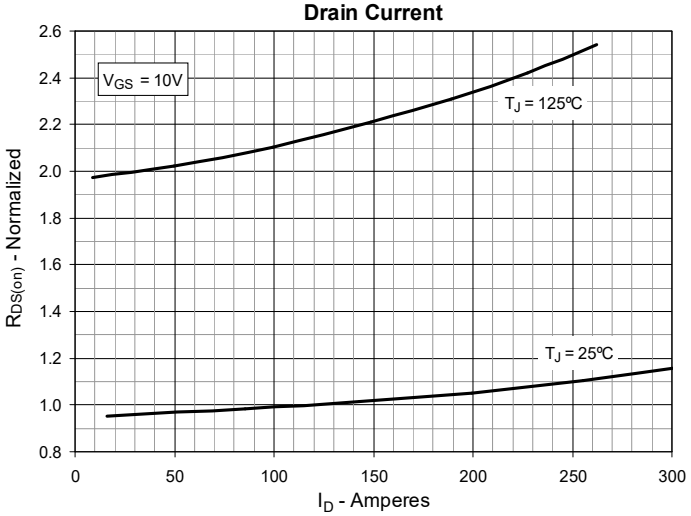


Fig. 6. Maximum Drain Current vs. Case Temperature

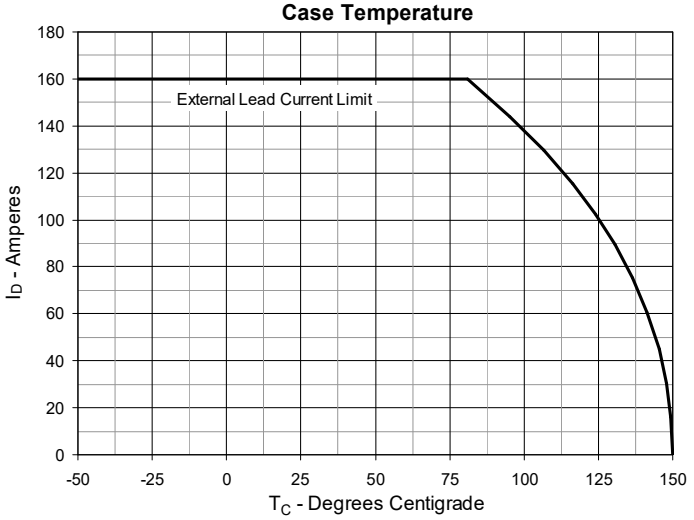


Fig. 7. Input Admittance

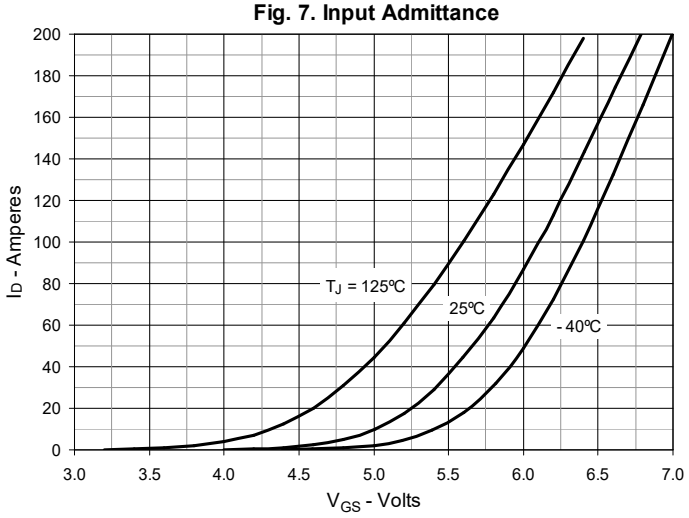


Fig. 8. Transconductance

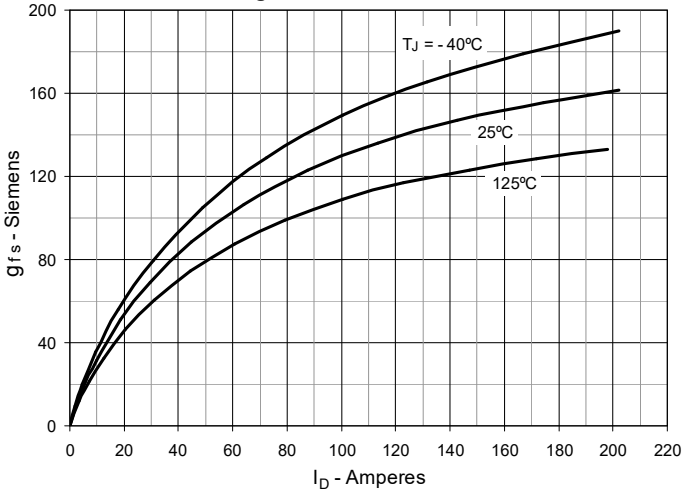


Fig. 9. Forward Voltage Drop of Intrinsic Diode

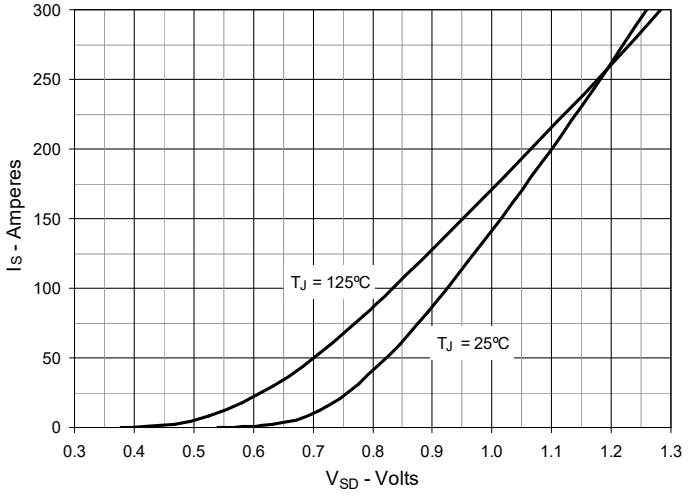


Fig. 10. Gate Charge

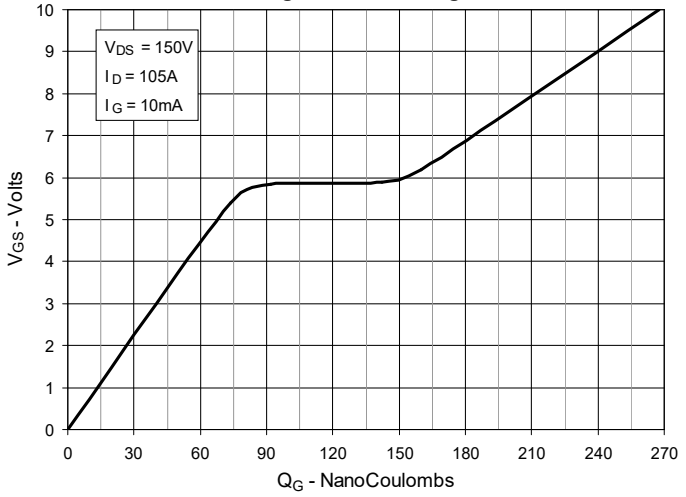


Fig. 11. Capacitance

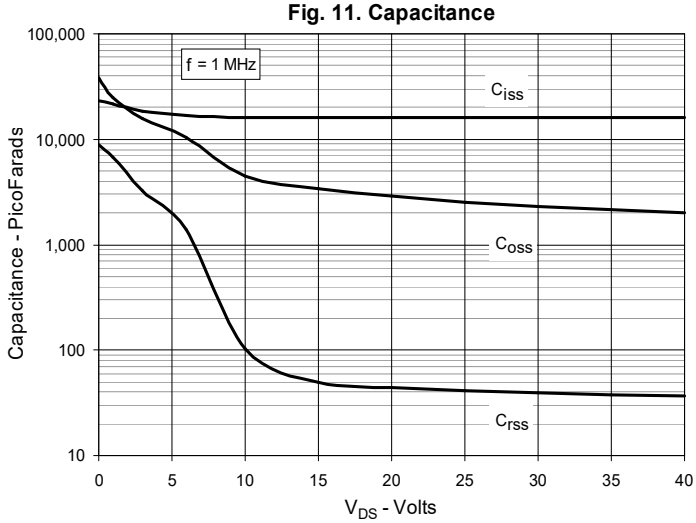


Fig. 12. Forward-Bias Safe Operating Area

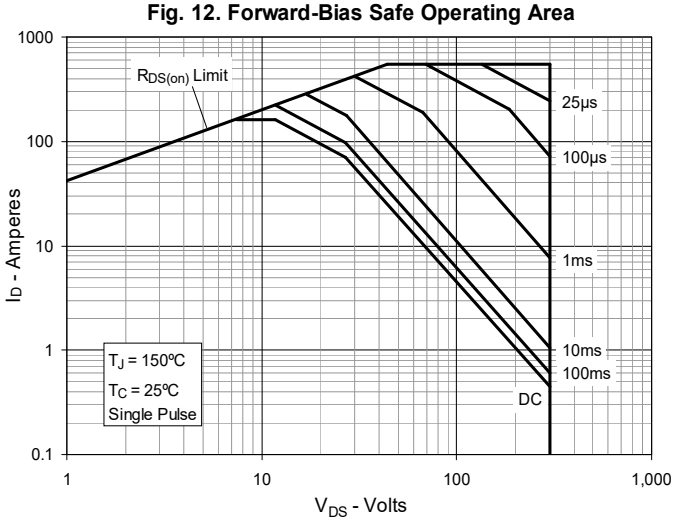
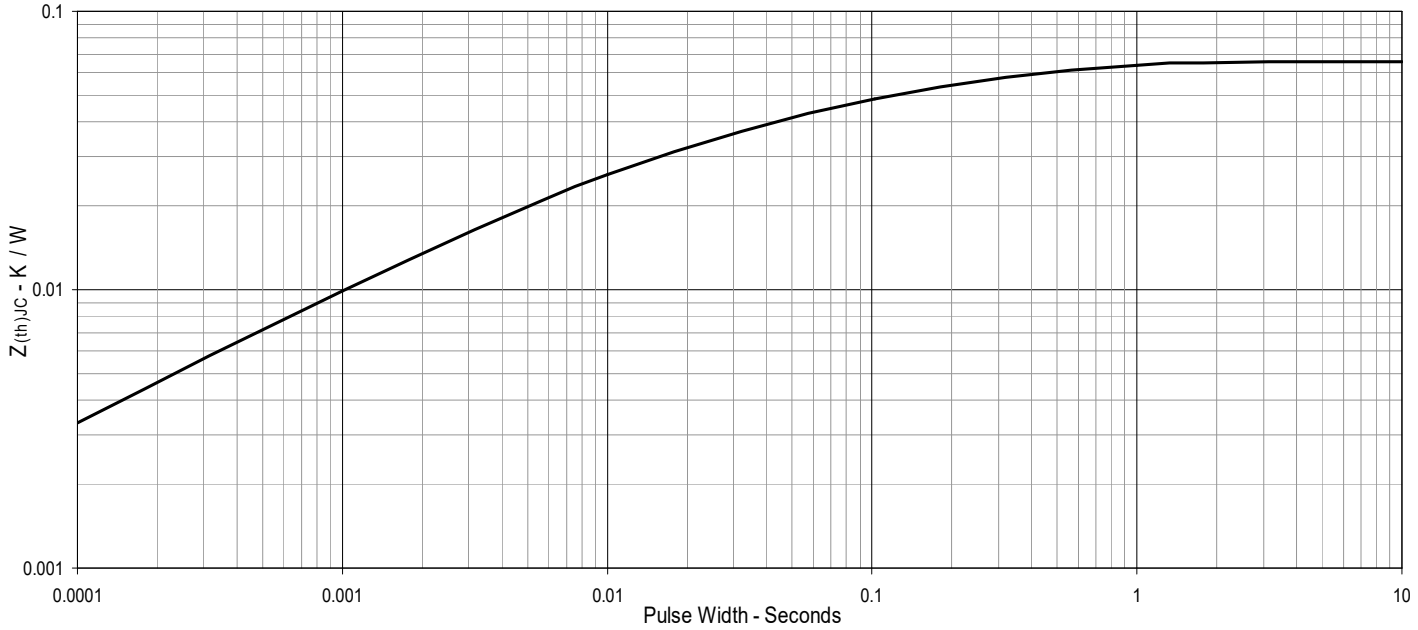
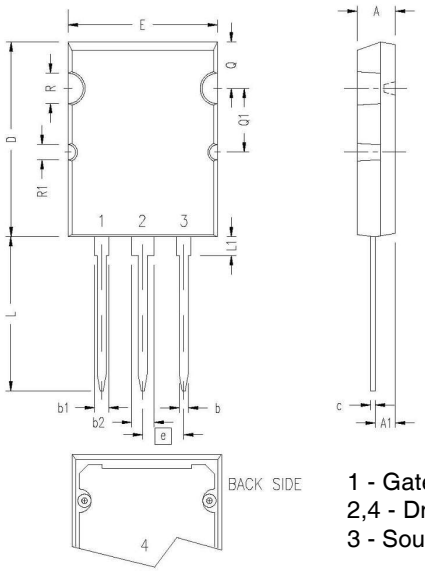


Fig. 13. Maximum Transient Thermal Impedance



PLUS264™ (IXFB) Outline



1 - Gate
2,4 - Drain
3 - Source

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215 BSC		5.46 BSC	
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36